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(21) International Application Number: PCT/US99/01639 (22) International Filing Date: 27 January 1999 (27.01.99) (30) Priority Data: 60/073,194 30 January 1998 (30.01.98) US (71) Applicant: E.I. DU PONT DE NEMOURS AND COMPANY [US/US]; 1007 Market Street, Wilmington, DE 19898 (US). (72) Inventors: BEITINGER, Gunter; Am Stocken 36, D-92318 Neumarkt (DE). KOLBECK, Gerald; Graf-Luckner-Strasse 7, D-92224 Amberg (DE). (74) Agent: PHAM, Hanh, T.; E.I. du Pont de Nemours and Company, Legal Patent Records Center, 1007 Market Street, Wilmington, DE 19898 (US).		(81) Designated States: CA, CN, JP, KR, SG, European patent (AT, BE, CH, CY, DE, DK, ES, FI, FR, GB, GR, IE, IT, LU, MC, NL, PT, SE). Published <i>With international search report.</i>
(54) Title: PROCESS FOR METAL PLATING LIQUID CRYSTALLINE POLYMERS AND COMPOSITIONS RELATED THERETO		
(57) Abstract Liquid crystalline polymers (LCP) may be sputter-coated or ion-plated with palladium to yield palladium coated LCP parts. These may be electrolytically plated, as with copper, using normal or unusually high current densities, to make metal plated LCP in which the metal has good adhesion to the LCPs. Before or after the electrolytic plating, the metal coating may be patterned. Parts containing patterned metal surface may be used as circuit boards or printed wire boards.  *162162*  *G00002*		